



Material Composition Declaration

EPC2038

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/24/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	1.1791	87.7042	90.2296	877042
	Silicon oxide	7631-86-9	0.0047	0.3520		3520
	Silicon nitride	12033-89-5	0.0019	0.1450		1450
	Gallium nitride	25617-97-4	0.0059	0.4375		4375
	Aluminum	7429-90-5	0.0085	0.6351		6351
	Aluminum nitride	24304-00-5	0.0012	0.0929		929
	Titanium	7440-32-6	0.0002	0.0184		184
	Titanium nitride	25583-20-4	0.0012	0.0871		871
	Copper	7440-50-8	0.0001	0.0106		106
	Tungsten	7440-33-7	0.0000	0.0024		24
	Polyimide		0.0100	0.7445		7445
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0059	0.5023	59
	Copper	7440-50-8	0.0067	0.4964		4964
Solder Bump	Tin	7440-31-5	0.1190	8.8509	9.2680	88509
	Silver	7440-22-4	0.0050	0.3707		3707
	Copper	7440-50-8	0.0006	0.0463		463
Sum in total:			1.3444	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.